SPECTRUM CONTROL, INC.

Control Products Systems Company



EMI

- **What are the repercussions**
- **What applications are prone to EMI**
- **M** Know what specifications apply to you
- **Types of filters**
- **☑** Basic circuits of "Low Pass" filters
- **☑** I/O impedance & selection criteria
- **Propagation Modes & Methods of suppression**
- **☑** Timing impact



- Cause catastrophic system failure in avionics equipment, or a piece of medical instrumentation may provide a false vital sign on a patients condition.
- This electrical energy could simply cause poor quality reception, & possible dropped calls and other system deteriorating





Microcell Repeaters

Switching Power Supplies

RF Amplifiers

Frequency Synthesizers

I Linear Power Amplifiers

Medical Electronics

Digitally Tuned Oscillators Automotive Controls





North America

FCC Part 15- Telecommunications Industry

FDA Regulations: Medical Industry

☑ Mil - STD- 461 and DO160: Military and Aerospace Industry

European Regulations

European Directive 89/336/ EEC: Regulation for all electronic devices and electrical equipment used in Europe. All products imported to the European community must conform to these regulations.

Generic Emissions

- **Marce EN 50081-1: Residential, Commercial, & Light Industrial**
- **EN 50081-2: Industrial Environment**

Specific Emissions

- **EN 55011: Conducted & Radiated for Industrial, Scientific & Medical**
- **EN 55014: Conducted & Radiated for Household Appliances**
- **EN 55022:** Conducted & Radiated for Information Technology Equipment
- EN 60555-2/3: Harmonics & Voltage Fluctuations in Household Equipment. Deals with Power Factor Corrections

Standards & Specifications Cont'd. SPECTRUM CONTROL, INC.

European Regulations Cont'd

Generic Immunity

- ☑ EN 50082-1: Residential, Commercial, & Light Industrial
- **EN 50082-2: Industrial Environment**

Specific Immunity

- ☑ EN 61000-4-1: Basic Immunity document, not a specific test
- ☑ EN 61000-4-2: ESD, Electrostatic Discharge
- ☑ EN 61000-4-3: Radiated RF Fields, radiated immunity
- ✓ EN 61000-4-4: EFT, Electrical Fast Transients, AC mains and I/O cable conducted immunity.
- ☑ EN 61000-4-5: Surge, AC mains conducted immunity
- **EN 61000-4-6: Conducted RF Fields**
- ☑ EN 61000-4-8: Power frequency magnetic field immunity
- ☑ EN 61000-4-9: Pulsed magnetic field immunity
- ☑ EN 61000-4-10: Damped Oscillatory field immunity
- ☑ EN 61000-4-11: Voltage dips, interruptions, and variations













The Basic Circuits of Low Pass Filters Using a 50 ohm Source & 50 ohm Load





The Basic Circuits of Low Pass Filters Using a 50 ohm Source & 50 ohm Load



















Radiated Emissions

Emitting Equipment

Susceptible Equipment

Methods of Suppression



Radiated Emissions - Shield







Conducted Emissions





Conducted Emissions - Filters







Radiated Conducted





Radiated Conducted-Shield / Filters







Conducted Radiated





Conducted Radiated - Filter / Shield





- // The further along in the design cycle, the more challenging & more costly the solution.
- Consult and ask questions from the go, it may save you a considerable sum of money in design time and components.



Equipment Development, Time Scale





- 1. Create control plan and tabulate all known frequencies and waveshapes to predict EMI profile.
- 2. Filter Power Lines at immediate entry point.
- **3.** Filter al I/O lines and signal lines with selected tailored passband response filters.
- 4. Design all modules to have an aluminum stiffener backplane under P.C board that bonds to printed circuit commons.
- 5. Use multilayer boards wherever possible to contain fast rise time energy.



- 6. Monitor Surface resistively of plating on all metal finishes to maintain less than 3 milliohms per square centimeter R.
- 7. Install ferrite cores / beads over input power lines and signal lines, coax lines etc. to minimize common mode emissions.
- 8. Twist all pairs of wires at 18 turns per foot to minimize magnetic pickup.
- 9. Shield and wiper ground / bond all backplanes and interfaces to modules.
- **10.** Close or interbond all apertures and gaps longer greater than Lambda (wavelength) / 20.



1. Create control plan and tabulate all known frequencies and waveshapes to predict EMI profile.

1992 European EMC Standards



Emission Standards: EN 55 022 Class B (Conducted Emission Radiated Emission)

	Freq Range	Limits
Radiated	30 - 230 MHz 230 - 1000 MHz	30 dB μV/m @ 10 m 37 dB μV/m @ 10 m
Conducted	0.15 - 0.5 MHz	$66 \rightarrow 56~dB\mu V$ quasi pk $56 \rightarrow 46~dB\mu V$ ave
	0.5 - 5 MHz	56 dBμV quasi pk 46 dBμV ave
	5 - 30 MHz	60 dBμV quasi pk 50 dBμV ave



Time Domain



Frequency Domain







4.08 MHz Expected Harmonics

	nt	FREQ.		n ^{ti}	FREQ.
f	= 1_	25 111	40 dB/decade	21	85.68
	πT=3.183 Mh	z			
100 dBuV	1	4.08			
20 dB/decade	2	8.16		22	89.76
	3	12.24		23	93.84
	4	16.32		24	97.92
	5	20.40		25	102.00
	6	24.48		26	106.08
	7	28.56		27	110.16
	8	32.64	14-02	28	114.24
	9	36.72		29	118.32
8	10	40.80		30	122.40
	11	44.88		31	126.48
	12	48.96	65 dBuV <u>1</u>		
			(-12 dB) f= 2x πτ,	= 127.32MH	k i
S			40 dB/Decade	32	130.56
	13	53.04		33	134.64
	14	57.12		34	138.72
2	15	61.20		35	142.80
77 dBuV f = <u>1</u>				36	146.88
πτ, = 63	662 Mhz				
40 dB / Decade	16	65.28			
	17	69.36		37	150.95
	18	73.44		38	155.04
	19	77.52		39	159.12
	20	81.60	60.65 dBuV	40	163.20
			(- 16.35 dB)		
			40 dB/decade	41	167.25
					etc.
			37 dBuV	156	636.62
			Frequency List		



2. Filter Power Lines at immediate entry point.





CABLE SHIELD

Wrong Power Filter Installation





Correct Filter Installation







3. Filter al I/O lines and signal lines with selected tailored passband response filters.





Chip Cap vs. Tubular 1000pF PI-Style vs. C-Style





Typical Insertion Loss

Chip Results Actual

Insertion Loss in Decibel (dB)





Spectrum Control, Inc. 10,000pF Chip Cap Filter Plate (Plate tested in a coaxial test fixture)

L-Section Filters





Frequency



Pi-Section Filters



Frequency



4. Design all modules to have an aluminum stiffener backplane under P.C board that bonds to printed circuit commons.

ALUMINUM GROUND PLANE FASTENED TO PRINTED CIRCUIT BOARD







5. Use multilayer boards wherever possible to contain fast rise time energy.



MULTILAYER PC BOARD PROVIDES I/O ISOLATION FROM POWER GROUND LAYER 3 SERVES AS Vcc COMMON



6. Monitor Surface resistively of plating on all metal finishes to maintain less than 3 milliohms per square centimeter R.



SURFACE RESISTIVITY OF PLATING



7. Install ferrite cores / beads over input power lines and signal lines, coax lines etc. to minimize common mode emissions.

Ferrite Beads







Ferrite Bead Filtering

•Select bead Z at Fo from Data Steward type 25 is 170 ohm @ 100MHz =Zf •Determine Z source = 100 ohm , Z load=500 ohm

SOURCE

LOAD

$$20 \quad \log \quad \frac{Z \text{ sodr.} Z_E}{Z + Z \text{ ource}} = 20 \quad \log \quad \frac{100 + 500}{170 + 100 + 500}$$

= 2.16 dB

$$100 \text{ ohm}$$

$$170 \text{ ohm}$$

$$170 \text{ ohm}$$

$$100 \text{ pF}$$

$$300 \text{ ohm}$$

$$100 \text{ pF}$$

$$300 \text{ ohm}$$

$$100 \text{ pF}$$

$$300 \text{ ohm}$$

$$100 \text{ MHz}$$

$$15.9 \text{ ohm}$$

$$20 \text{ log} \frac{Z \text{ sorts} Ze}{Z \neq Z} \frac{LT}{Z \neq Z + Z_{OURCE}} LT = 20 \text{ log} \frac{100 + 15.41}{170 + 100 + 15.41}$$

$$= 7.86 \text{ dB}$$





FREQUENCY (MHz)

Impedence vs. DC Bias Common vs. Differential Mode





FREQUENCY (MHz)





Contracting Killing	- 523 - C.	产于国际中心和国际市场。1992年2月20日	A CONTRACTOR OF A CARLENA OF A	AND STREET, SALAR STREET, S	CONTRACTOR TO CAR	(2)将(2):	enni eennietere
25 Material	100 - 500	125	3650 @ 10 Oe	2600	1.6	≥ 225° C	108
28 Material	30 - 300	850	3350 @ 10 Oe	2200	0.4	≥ 175° C	105
29 Material	30 - 300	600	3300 @ 10 Oe	1500	0.35	≥ 165° C	108





Property Units	Frequency Range MHz	Initial Permeability (۱.)	Saturation Flux Density (B ₅) Gauss	Residual Flux Density (B _r) Gauss	Coercive Force H _C	Curie Temperature (T _C) ° C	Volume Resistivity (p) Ohm-Centimeters
25 Material	100 - 500	125	3650 @ 10 Oe	2600	1.6	≥ 225° C	108
28 Material	30 - 300	850	3350 @ 10 Oe	2200	0.4	≥ 175° C	105
29 Material	30 - 300	600	3300 @ 10 Oe	1500	0.35	≥ 165° C	10 ⁸



8. Twist all pairs of wires at 18 turns per foot to minimize magnetic pickup.

RELATIVE SUSCEPTIBILITY OF CIRCUITS TO MAGNETIC INTERFERENCE





VALUES GIVEN ARE FOR CIRCUITS 1 INCH ABOVE GROUND PLANE



9. Shield and wiper ground / bond all backplanes and interfaces to modules.



SHIELD BACKPLANE WIPER GROUND CARD



10. Close or interbond all apertures and gaps longer greater than Lambda (wavelength) / 20.





FREQ.	Max.Gap
120 MHz	4.92"
600 MHz	0.98"
1.5G Hz	0.394"
3.0 GHz	0.197"

$$\frac{3 \times 10^8 \times 39.37}{\text{FREQ.}} = \lambda$$
$$\frac{\lambda}{20} = \text{Aperture Max.}$$

simplified
$$\frac{591}{F \text{ MHz}} = \text{Max. GapInches}$$



Spectrum Control Contacts

Dave Arthurs – Product Field Specialist Tel – 814-474-4363 E-mail – <u>arthurs@spectrumcontrol.com</u>

Jeff Showers – North East Regional Manager Tel – 866-281-0288 E-mail – <u>showers@spectrumcontrol.com</u>